

CLAIMS

1. A wafer rotating device comprising:
 - at least three rollers rotatably provided about axes arranged at parallel intervals and which rotate over the circumferential surface of a disk-shaped wafer;
 - 5 a rotation drive mechanism that rotates and drives at least one of the rollers;
 - an interval adjustment mechanism capable of adjusting the dimensions of the intervals of the rollers; and,
 - a load control device that controls the load applied from the rollers to the wafer in the radial direction of the wafer when the wafer is clamped between the rollers.
- 10 2. A wafer rotating device according to claim 1 wherein, a load cell is provided in the interval adjustment mechanism that detects the load applied to the rollers along the direction of movement of the rollers, and
 - the load control device controls the interval adjustment mechanism so that the load
 - 15 detected by the load cell is maintained constant.
3. A wafer rotating device according to claim 1 wherein, in addition to the rollers being rotatably provided around axes arranged roughly in the vertical direction, a flange section having a diameter larger than the circumferential surface is provided below the
- 20 circumferential surface that clamps the wafer, and has an inclined surface in which the upper surface of the flange section gradually becomes lower moving towards the outside in the radial direction.
4. A wafer rotating device according to claim 1 wherein, the interval between the
- 25 other two rollers adjacent to the roller on both sides is smaller than 180°.

5. A wafer rotating device according to claim 4 wherein, pairs of rollers are arranged at three locations or more at intervals in the circumferential direction of a wafer.

6. An edge flaw inspection device comprising:

5 a wafer rotating device according to claim 1;

a light source that radiates light onto the circumferential surface of a wafer supported by the wafer rotating device; and,

a light detector that detects light that has been radiated from the light source which is reflected on the circumferential surface of the wafer.